POLYMER|G

EP 1140DV

High Thermal Conductive Epoxy Adhesive

| **Product Description** | EP 1140DV, a two-component, thermal conductive epoxy adhesive, offers excellent electrical insulation characteristics together with low thermal expansion and high chemical resistance. EP 1140 DV demonstrates high adhesion to metals and ceramics |

Features & Benefits

- High thermal conductivity
- Excellent electrical insulation
- High chemical resistance
- Low thermal expansion
- RT curing
- Long pot life

Applications Bonding and sealing

Typical Uncured Physical Properties

Note: The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

Base Resins	Base (A) Hardener (B)	Epoxy Polyamides
Appearance/Color	Base (A) Hardener (B)	black amber
Viscosity @ 25°C, mPa*s, ASTM-D-2393	Base (A) Hardener (B)	Soft paste 5500
Density, g/cm^3 @ 25°C	Base (A) Hardener (B)	2.2 1.0
Mix Ratio (A:B), by vol.	4:1	

Typical Cured Properties

Note: **The following technical information and data should be considered representative or typical only and should not be used for specification purposes.**

Color	black
Hardness, Shore D	87
Gel Time (2-3mm layer @ 25°C), min	60-80
Initial Curing @ 25°C, hr	6-8
Final Curing @ 25°C, hr	24
Lap Shear Strength, etched Al, MPa	19
Thermal Conductivity, W/m-K	1.1
Operating Temperature, °C	-40 to 120

Storage

Store products at 18-30°C for maximum shelf life.

Packaging

4:1 50cc dual cartridges

Shelf Life

This product has a shelf life of 12 months in unopened dual cartridges

Limitation of Liability

Except where prohibited by law, Polymer-G and seller will not be liable for any loss or damage arising from the Polymer-G product, whether direct, indirect, special, incidental or consequential, regardless of the legal theory asserted, including warranty, contract, negligence or strict liability.